PCN Number:		20140130000							PCN Date: 02/0		02/04/2014		
Title:	Title: Qualification of JCET as Alternate Assembly/Test site for select UQFN Devices												
Customer Contact:		PCN Manager			Phone:	+1(214)480-6037			Dept:	Quality Services			
Proposed 1st Ship Da		te: 05/04/2014		Estim	timated Sample Avai			bility:	01/31/2014				
Change Type:													
Asse	embly Site			Assembly F	Process			Asse	sembly Materials				
Des	ign			Electrical S	pecificati	ion		Mec	echanical Specification				
Test	Test Site			Packing/Shipping/Labeling					Test Process				
Waf	er Bump Site				mp Material			Waf	Wafer Bump Process				
Waf	Wafer Fab Site Wafer Fa				Materials Wa				afer Fab Process				
			Part number change										
PCN Details													
Description of Change:													
Texas Instruments is pleased to announce the qualification of Jiangsu Changjiang Electronics Technology Co (JCET) as an alternate assembly and test site for Select UQFN devices. JCET will use the same BOM as the existing site.													
Reason	for Change:												

Changes to product identification resulting from this PCN:

Assembly Site		
JCAPAT	Assembly Site Origin (22L)	ASO: JCP
JCET	Assembly Site Origin (22L)	ASO: JCE

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Sample product shipping label (not actual product label)



(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483\$I2 (P) (2P) REV: (V) 0033317 (20L) C\$0: SHE (21L) CCO: USA (22L) A\$0: MLA (23L) ACO: MYS

Topside Device marking:

Continuity of Supply

None

Assembly site code for JCP= P Assembly site code for JCE= F

Product Affected					
LMV881LE/NOPB	LMV881LEE/NOPB	LMV881LEX/NOPB			

0 1:0				2011		
Qualification Data - Approved January, 2014						
This qualification has been specifically developed for the validation of this change. The qualification data						
validates that the proposed change meets the applicable released technical specifications.						
Qual Vehicle: LMV881LE/NOPB (MSL1-260C)						
Package Construction Details						
Assembly & Bump Sit	e:	JCET	Mold Compound:		013101008701	
# Pins-Designator, Fami	y:	6-NKK, UQFN	Flux:		120404001100	
Contact typ	e:	Cu Pillar				
Qualification: Plan Test Results						
Reliability Test		Conditions			mple S	Size/Fail
					†1	Lot#2
**Biased HAST		130C/85%RH (96 Hrs)		77/0		77/0
**Autoclave 121C		121C, 2 atm (96 Hrs)			0	77/0
**T/C -65C/150C		130C/85%RH (96 Hrs)			0	77/0
ESD CDM		+/- 250V, 500V			S	
Physical Dimensions		(per mechanical drawing)			S	pass
** - Test requires Moisture Precon	ditio	oning (MSL1-260C)				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com